

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>SEQUENCE:</b>	4	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	JING WANG	01/17/2017
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<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	16737670
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>	(312)427-6663	
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<b>ATTORNEY DOCKET NUMBER:</b>	CU-74610 RJS/MF-4	
<b>NAME OF SUBMITTER:</b>	RICHARD J. STREIT	
<b>SIGNATURE:</b>	/Richard J. Streit/	
<b>DATE SIGNED:</b>	03/09/2020	

**Total Attachments: 2**

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WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full right to convey the same as herein expressed is possessed by the undersigned;

COVENANT, when requested and at the expense of the Assignee, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all such inventions; execute all rightful oaths, declarations, assignments, powers of attorney and other papers; communicate to the Assignee all facts known to the undersigned relating to such inventions and the history thereof; and generally do everything possible which the Assignee shall consider desirable for vesting tide to such inventions in the Assignee, and for securing, maintaining and enforcing proper patent protection for such inventions;

TO BE BINDING on the heirs; assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignee.

ASSIGNOR HEREBY REPRESENTS AND WARRANTS that ASSIGNOR has the full and unencumbered right to sell, assign, and transfer the interests sold, assigned, and transferred herein, and that ASSIGNOR has not executed and will not execute any document or instrument in conflict herewith.

ASSIGNOR HEREBY GRANTS to the agents and attorneys of \_\_\_\_\_ the power and authority to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

The assignment of said invention is effective as of the earlier of (1) the date of execution shown below or (2) the filing date of the first filed of said patent applications.

**STATEMENTS**

I have reviewed and understand the contents of the above-identified application, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the United States Patent Office all information known to me to be material to patentability as defined in 37 C.F.R. 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part.

LEGAL NAME OF INVENTOR	
Inventor: _____	Date: <u>Jan. 17, 2017</u>
Signature: <u>Jing WANG</u>	